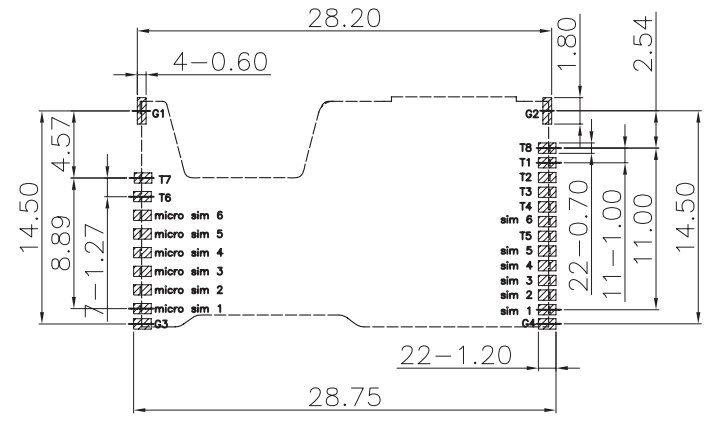
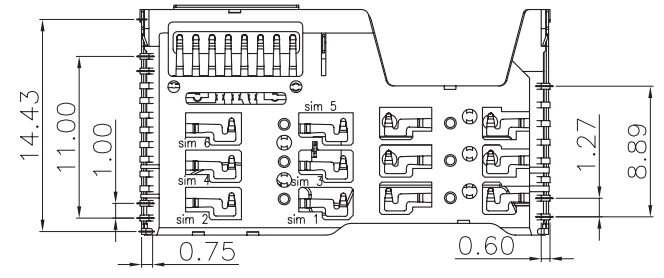
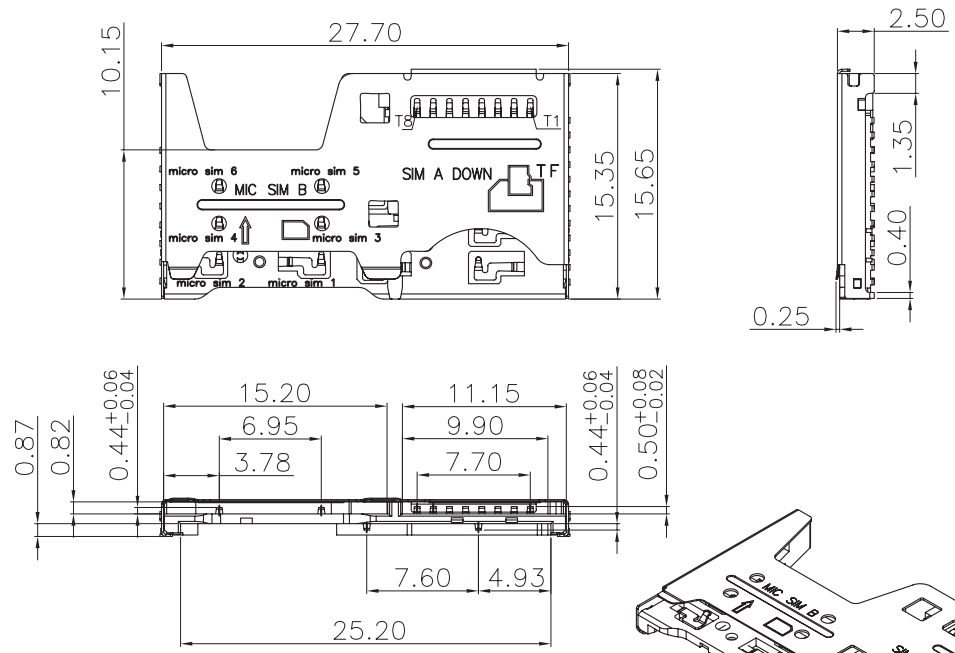


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2013/09/11



NOTES:

- Material:  
Housing: HI-Temp plastic UL 94V-0  
Contact: Copper Alloy  
Shell: STAINLESS STEEL
- Finish :  
CONTACT: G/F" Gold plated on contact area;  
G/F" Gold plated on solder tails, Base Nickel :50u"Min  
SHELL: 50u" NICKEL UNDER, G/F on solder tails

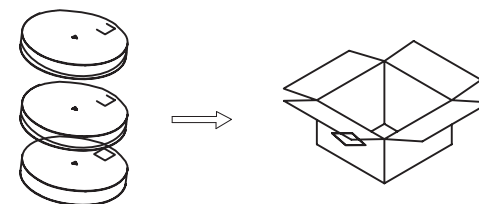
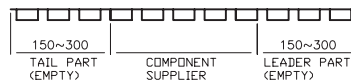
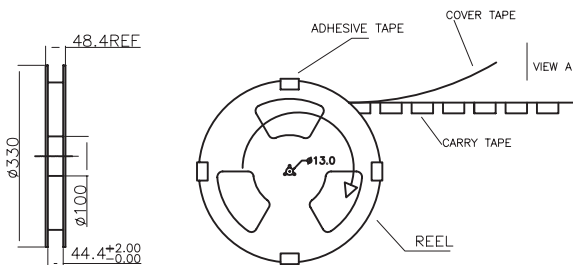
SIM CARD PIN NO.	PIN NAME	MICRO SIM CARD PIN NO.	PIN NAME	SIM CARD PIN NO.	PIN NAME
T1	DAT2	micro sim 1	GND	sim 1	GND
T2	CD/DAT3	micro sim 2	VCC	sim 2	VCC
T3	CMD	micro sim 3	VPP	sim 3	VPP
T4	VDD	micro sim 4	RST	sim 4	RST
T5	CLK	micro sim 5	I/O	sim 5	I/O
T6	VSS	micro sim 6	CLK	sim 6	CLK
T7	DATO	SHELL NAIL PIN NO.		PIN NAME	
T8	DAT1	G1~G4		GROUND	

RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES: ±0.05

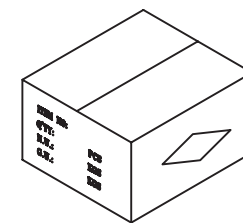
▨ PAD AREA    □ KEEP OUT AREA

GENERAL TOLERANCE		图号	LZA0911-001	设计	WEND	比例	1:1
X.±0.20	x.'±5'	品名	2.50H 三合一 CARD SMT TYPE CONN	审核		单位	mm
.X±0.15	.x'±2'			核准		视角	☉
.XX±0.08	.xx'±1'	料号	ASMFS250S01BR044	日期	2013/09/11	版本	A0
.XXX±0.05	.xxx'±0.5'	东莞市汉硕电子科技有限公司					
页数	1/1						

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/04/13

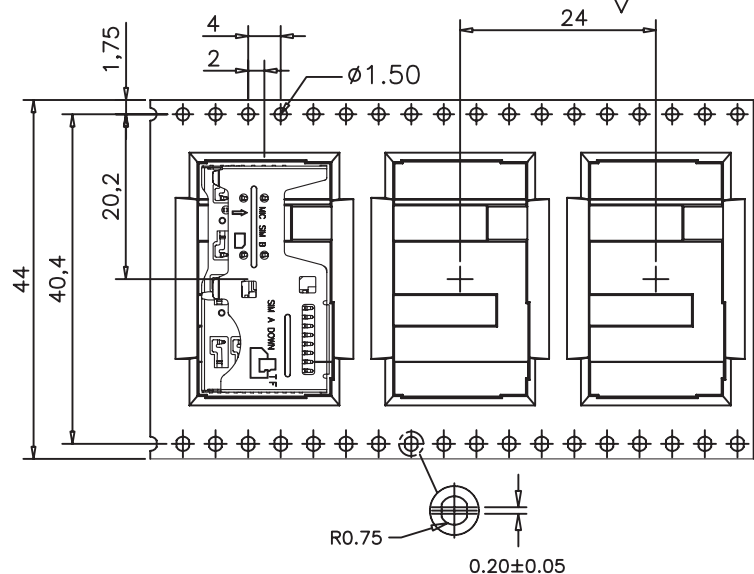


每箱装7盘, 依次叠在一起(图一)

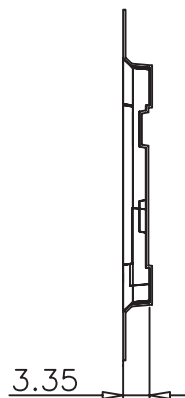


封箱, 填写相关内容(图二)

对应三视图



图示三



NOTE:

1. CARRY TAPE(黑色)前部分与尾部分各留出150~300mm长度不装产品
2. 每穴放置1PCS产品, 放置方式如图所示
3. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签
4. 包装数量: 750PCS/REEL, 7REEL/CARTON, 5250PCS/CARTON
5. 依次将产品放入箱内, 共放7盘(图示一)
6. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等(图示二)
7. 顺向出料, 单孔朝外。
8. 顺向出料, 双孔按图示三

GENERAL TOLERANCE		DWG NO.	LZA0422-011	APPD:	WIND	Scale	1:1
X.±0.45	x.±5°	Title	2.5H 三合一 CARD CONN 包装图	CHKD:		UNIT	mm
.X±0.35	.x'±2°			DR:			
.XX±0.25	.xx'±1°	Part NO.		Date	2014/04/13		
.XXX±0.15	.xxx'±0.5°						
SHEET	1/1	东莞市汉硕电子科技有限公司					